

Title (en)

METHOD AND DEVICE FOR PRODUCING A CUTOUT OR APERTURE IN THE WALL OF A COMPONENT FORMED ACCORDING TO THE HYDROFORMING PROCESS

Title (de)

VERFAHREN UND VORRICHTUNG ZUM HERSTELLEN EINES AUSSCHNITTES ODER DURCHBRUCHS IN DER WANDUNG EINES NACH DEM INNENHOCHDRUCK-UMFORMVERFAHREN AUSGEBILDETEN BAUTEILS

Title (fr)

PROCEDE ET DISPOSITIF DE Formation D'UNE DECOUPE OU D'UNE PERFORATION DANS LA PAROI D'UN COMPOSANT FORME PAR UN PROCEDE DE FACONNAGE SOUS HAUTE PRESSION INTERIEURE

Publication

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Application

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Abstract (en)

[origin: WO2007093269A1] The invention relates to a method of producing a cutout or aperture in the wall of a component formed according to the hydroforming process, for example a hollow body which is located in the forming tool (1), by means of a punch (8, 10) which is displaceable from outside to inside or from inside to outside and which is pressed into the wall of the hollow body. In order to carry out a cutting process in the tool, it is proposed that the wall of the initial workpiece or workpiece mounted in the forming tool (1) and fixed and positioned preferably with sealing plungers (3, 4) first of all be precut abruptly by means of the punch (8, 10) except for a residual wall thickness. The forming process is combined with processes of chipless forming for processing the apertures and cutouts and with finishing, which take place in the tool. Furthermore, a corresponding device is proposed.

IPC 8 full level

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